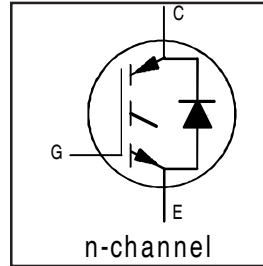


IRG4PC50UDPbF

INSULATED GATE BIPOLAR TRANSISTOR WITH ULTRAFAST SOFT RECOVERY DIODE UltraFast CoPack IGBT

Features

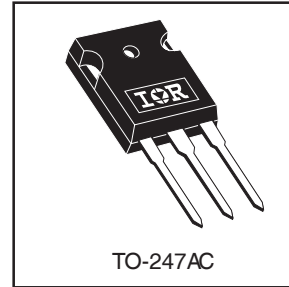
- UltraFast: Optimized for high operating frequencies 8-40 kHz in hard switching, >200 kHz in resonant mode
- Generation 4 IGBT design provides tighter parameter distribution and higher efficiency than Generation 3
- IGBT co-packaged with HEXFRED™ ultrafast, ultra-soft-recovery anti-parallel diodes for use in bridge configurations
- Industry standard TO-247AC package
- Lead-Free



$V_{CES} = 600V$
$V_{CE(on) typ.} = 1.65V$
@ $V_{GE} = 15V, I_C = 27A$

Benefits

- Generation 4 IGBT's offer highest efficiencies available
- IGBT's optimized for specific application conditions
- HEXFRED diodes optimized for performance with IGBT's. Minimized recovery characteristics require less/no snubbing
- Designed to be a "drop-in" replacement for equivalent industry-standard Generation 3 IR IGBT's



Absolute Maximum Ratings

	Parameter	Max.	Units
V_{CES}	Collector-to-Emitter Voltage	600	V
$I_C @ T_C = 25^\circ C$	Continuous Collector Current	55	A
$I_C @ T_C = 100^\circ C$	Continuous Collector Current	27	
I_{CM}	Pulsed Collector Current ①	220	
I_{LM}	Clamped Inductive Load Current ②	220	
$I_F @ T_C = 100^\circ C$	Diode Continuous Forward Current	25	
I_{FM}	Diode Maximum Forward Current	220	W
V_{GE}	Gate-to-Emitter Voltage	± 20	
$P_D @ T_C = 25^\circ C$	Maximum Power Dissipation	200	W
$P_D @ T_C = 100^\circ C$	Maximum Power Dissipation	78	
T_J	Operating Junction and	-55 to +150	°C
T_{STG}	Storage Temperature Range		
	Soldering Temperature, for 10 sec.	300 (0.063 in. (1.6mm) from case)	
	Mounting Torque, 6-32 or M3 Screw.	10 lbf•in (1.1 N•m)	

Thermal Resistance

	Parameter	Min.	Typ.	Max.	Units
$R_{\theta JC}$	Junction-to-Case - IGBT	-----	-----	0.64	°C/W
$R_{\theta JC}$	Junction-to-Case - Diode	-----	-----	0.83	
$R_{\theta CS}$	Case-to-Sink, flat, greased surface	-----	0.24	-----	
$R_{\theta JA}$	Junction-to-Ambient, typical socket mount	-----	-----	40	
Wt	Weight	-----	6 (0.21)	-----	g (oz)

IRG4PC50UDPbF

Electrical Characteristics @ $T_J = 25^\circ\text{C}$ (unless otherwise specified)

	Parameter	Min.	Typ.	Max.	Units	Conditions
$V_{(BR)CES}$	Collector-to-Emitter Breakdown Voltage ^③	600	----	----	V	$V_{GE} = 0V, I_C = 250\mu A$
$\Delta V_{(BR)CES}/\Delta T_J$	Temperature Coeff. of Breakdown Voltage	----	0.60	----	V/ $^\circ\text{C}$	$V_{GE} = 0V, I_C = 1.0mA$
$V_{CE(on)}$	Collector-to-Emitter Saturation Voltage	----	1.65	2.0	V	$I_C = 27A$ $I_C = 55A$ $I_C = 27A, T_J = 150^\circ\text{C}$ $V_{GE} = 15V$ See Fig. 2, 5
		----	2.0	----		
		----	1.6	----		
$V_{GE(th)}$	Gate Threshold Voltage	3.0	----	6.0		$V_{CE} = V_{GE}, I_C = 250\mu A$
$\Delta V_{GE(th)}/\Delta T_J$	Temperature Coeff. of Threshold Voltage	----	-13	----	mV/ $^\circ\text{C}$	$V_{CE} = V_{GE}, I_C = 250\mu A$
g_{fe}	Forward Transconductance ^④	16	24	----	S	$V_{CE} = 100V, I_C = 27A$
I_{CES}	Zero Gate Voltage Collector Current	----	----	250	μA	$V_{GE} = 0V, V_{CE} = 600V$ $V_{GE} = 0V, V_{CE} = 600V, T_J = 150^\circ\text{C}$
		----	----	6500		
V_{FM}	Diode Forward Voltage Drop	----	1.3	1.7	V	$I_C = 25A$ $I_C = 25A, T_J = 150^\circ\text{C}$ See Fig. 13
		----	1.2	1.5		
I_{GES}	Gate-to-Emitter Leakage Current	----	----	± 100	nA	$V_{GE} = \pm 20V$

Switching Characteristics @ $T_J = 25^\circ\text{C}$ (unless otherwise specified)

	Parameter	Min.	Typ.	Max.	Units	Conditions
Q_g	Total Gate Charge (turn-on)	----	180	270		$I_C = 27A$
Q_{ge}	Gate - Emitter Charge (turn-on)	----	25	38	nC	$V_{CC} = 400V$ See Fig. 8
Q_{gc}	Gate - Collector Charge (turn-on)	----	61	90		
$t_{d(on)}$	Turn-On Delay Time	----	46	----		$V_{GE} = 15V$ $T_J = 25^\circ\text{C}$
t_r	Rise Time	----	25	----	ns	$I_C = 27A, V_{CC} = 480V$
$t_{d(off)}$	Turn-Off Delay Time	----	140	230		$V_{GE} = 15V, R_G = 5.0\Omega$ Energy losses include "tail" and diode reverse recovery. See Fig. 9, 10, 11, 18
t_f	Fall Time	----	74	110		
E_{on}	Turn-On Switching Loss	----	0.99	----		$T_J = 150^\circ\text{C}$, See Fig. 9, 10, 11, 18 $I_C = 27A, V_{CC} = 480V$
E_{off}	Turn-Off Switching Loss	----	0.59	----	mJ	
E_{is}	Total Switching Loss	----	1.58	1.9		$V_{GE} = 15V, R_G = 5.0\Omega$ Energy losses include "tail" and diode reverse recovery. Measured 5mm from package $V_{GE} = 0V$
$t_{d(on)}$	Turn-On Delay Time	----	44	----	ns	
t_r	Rise Time	----	27	----		$V_{CC} = 30V$ See Fig. 7
$t_{d(off)}$	Turn-Off Delay Time	----	240	----		
t_f	Fall Time	----	130	----		$f = 1.0MHz$ $T_J = 25^\circ\text{C}$ See Fig. $T_J = 125^\circ\text{C}$ 14 $I_F = 25A$
E_{is}	Total Switching Loss	----	2.3	----	mJ	
L_E	Internal Emitter Inductance	----	13	----	nH	$T_J = 25^\circ\text{C}$ See Fig. $T_J = 125^\circ\text{C}$ 15 $T_J = 125^\circ\text{C}$ 16
C_{ies}	Input Capacitance	----	4000	----		
C_{oes}	Output Capacitance	----	250	----	pF	$V_R = 200V$ $di/dt 200A/\mu s$
C_{res}	Reverse Transfer Capacitance	----	52	----		
t_{rr}	Diode Reverse Recovery Time	----	50	75	ns	$T_J = 25^\circ\text{C}$ See Fig. $T_J = 125^\circ\text{C}$ 14 $T_J = 125^\circ\text{C}$ 15 $T_J = 125^\circ\text{C}$ 16
		----	105	160		
I_{rr}	Diode Peak Reverse Recovery Current	----	4.5	10	A	$T_J = 25^\circ\text{C}$ See Fig. $T_J = 125^\circ\text{C}$ 15
		----	8.0	15		
Q_{rr}	Diode Reverse Recovery Charge	----	112	375	nC	$T_J = 25^\circ\text{C}$ See Fig. $T_J = 125^\circ\text{C}$ 16
		----	420	1200		
$di_{(rec)M}/dt$	Diode Peak Rate of Fall of Recovery During t_b	----	250	----	A/ μs	$T_J = 25^\circ\text{C}$ $T_J = 125^\circ\text{C}$
		----	160	----		

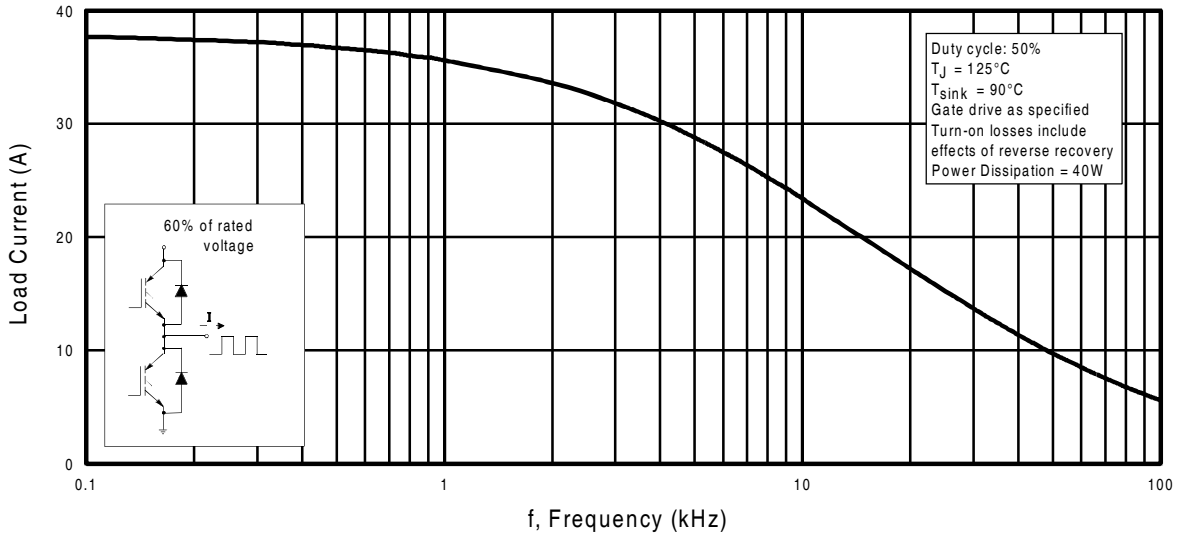


Fig. 1 - Typical Load Current vs. Frequency
 (Load Current = I_{RMS} of fundamental)

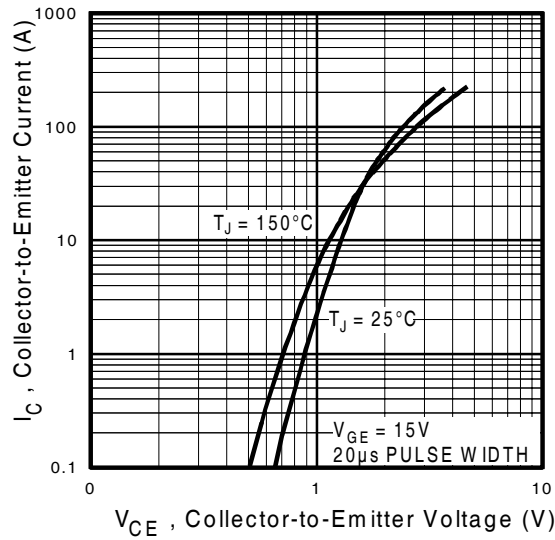


Fig. 2 - Typical Output Characteristics

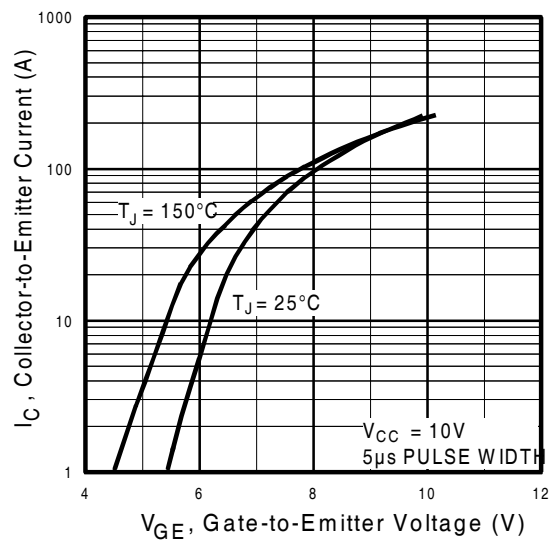


Fig. 3 - Typical Transfer Characteristics

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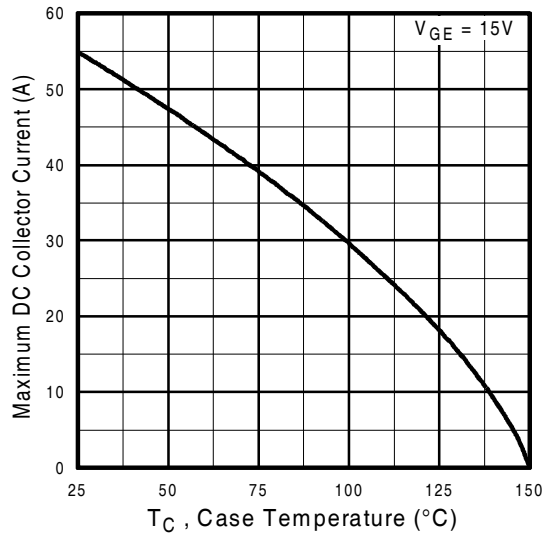


Fig. 4 - Maximum Collector Current vs. Case Temperature

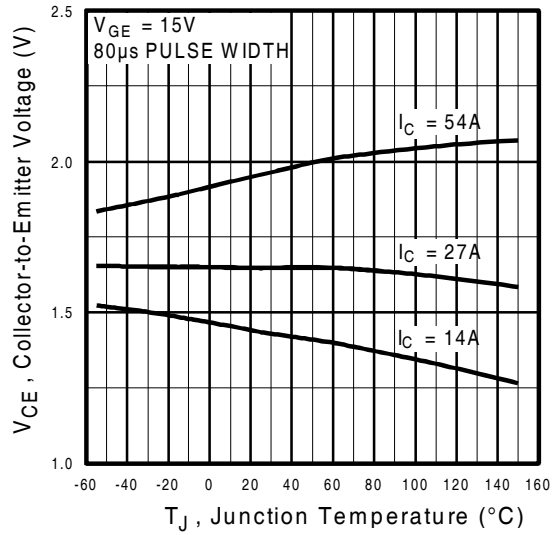


Fig. 5 - Typical Collector-to-Emitter Voltage vs. Junction Temperature

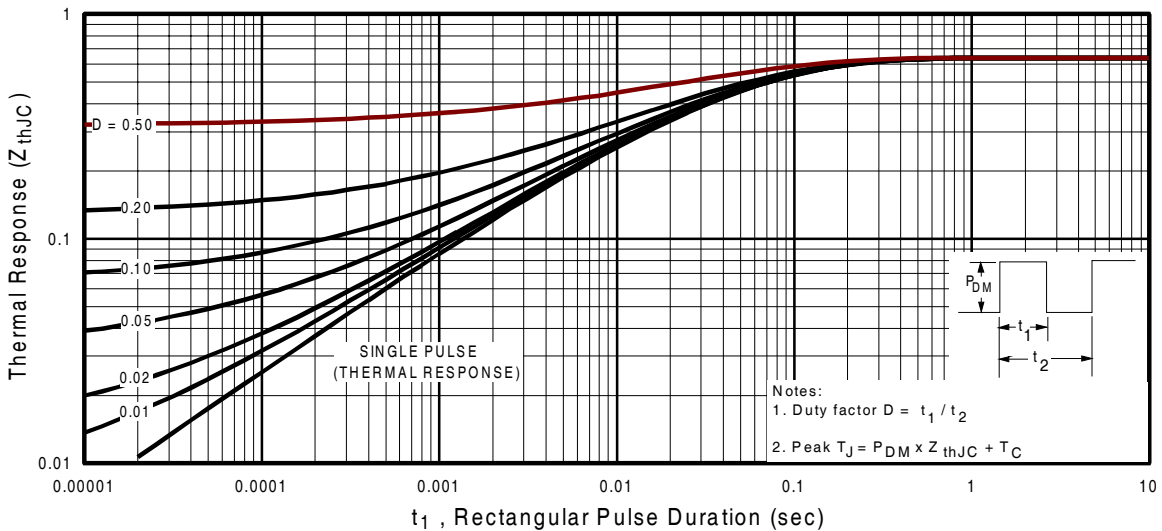


Fig. 6 - Maximum IGBT Effective Transient Thermal Impedance, Junction-to-Case

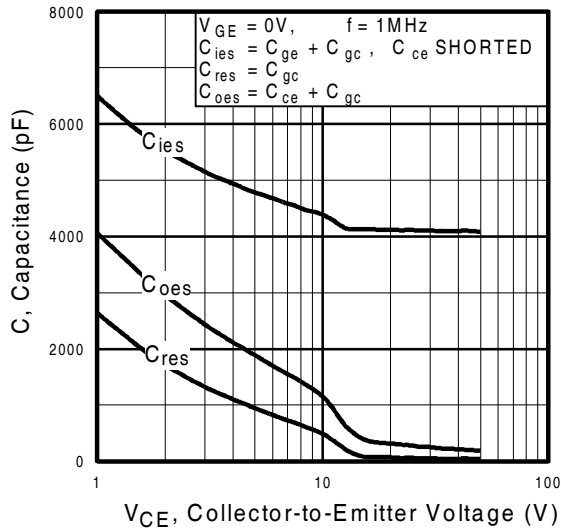


Fig. 7 - Typical Capacitance vs. Collector-to-Emitter Voltage

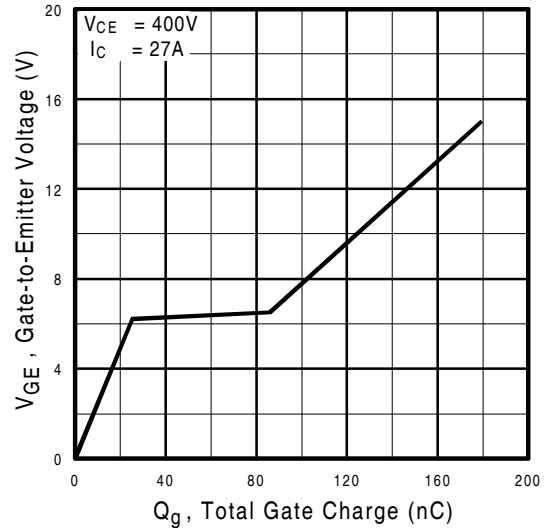


Fig. 8 - Typical Gate Charge vs. Gate-to-Emitter Voltage

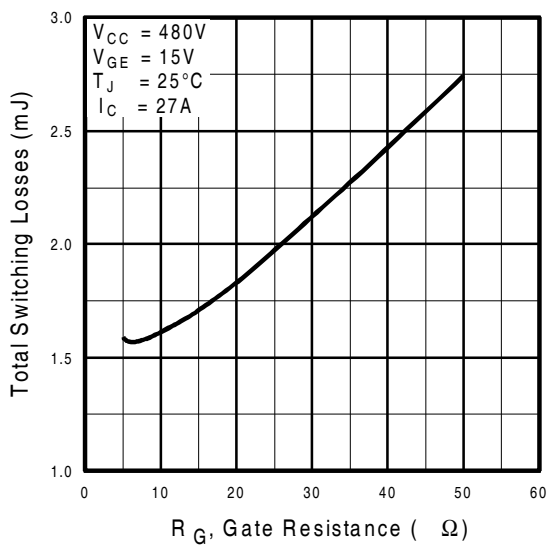


Fig. 9 - Typical Switching Losses vs. Gate Resistance

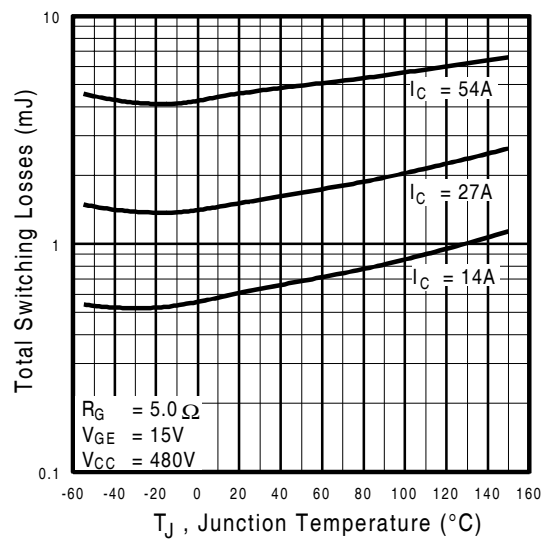


Fig. 10 - Typical Switching Losses vs. Junction Temperature

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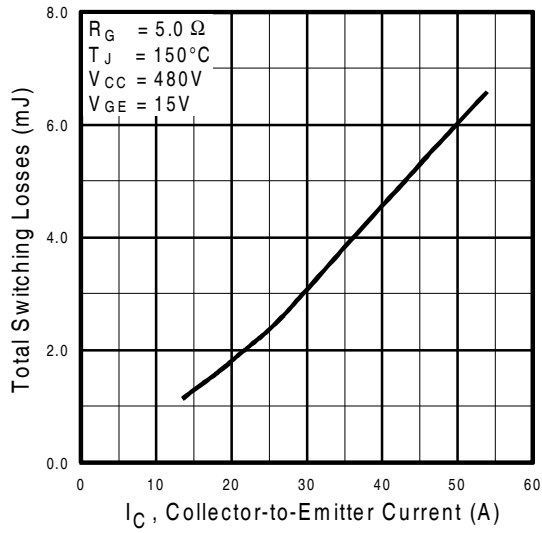


Fig. 11 - Typical Switching Losses vs. Collector-to-Emitter Current

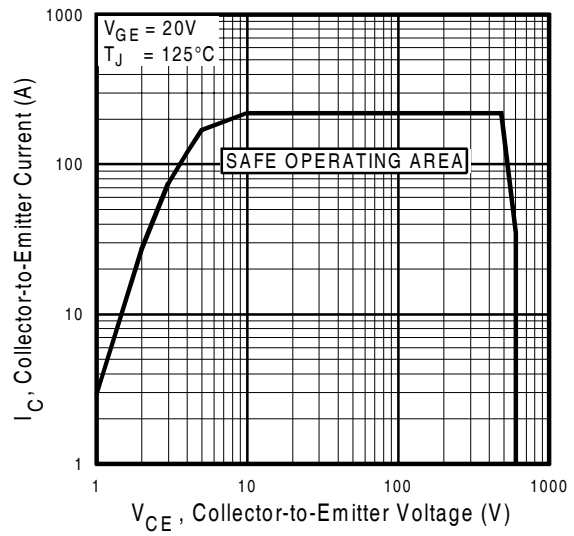


Fig. 12 - Turn-Off SOA

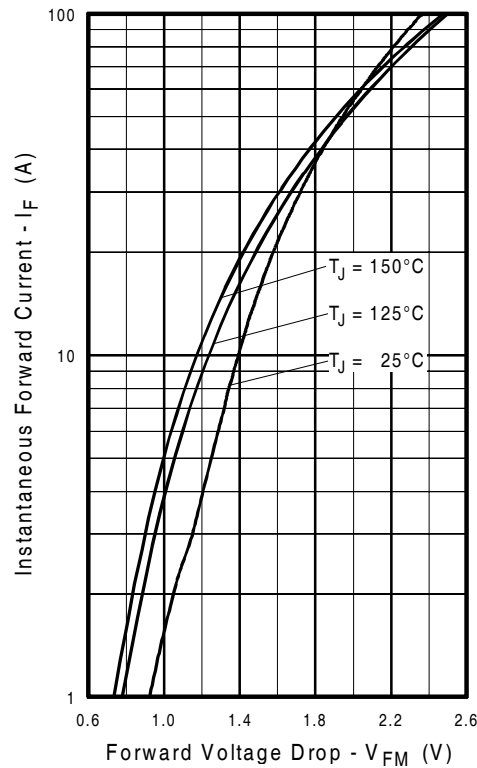


Fig. 13 - Maximum Forward Voltage Drop vs. Instantaneous Forward Current

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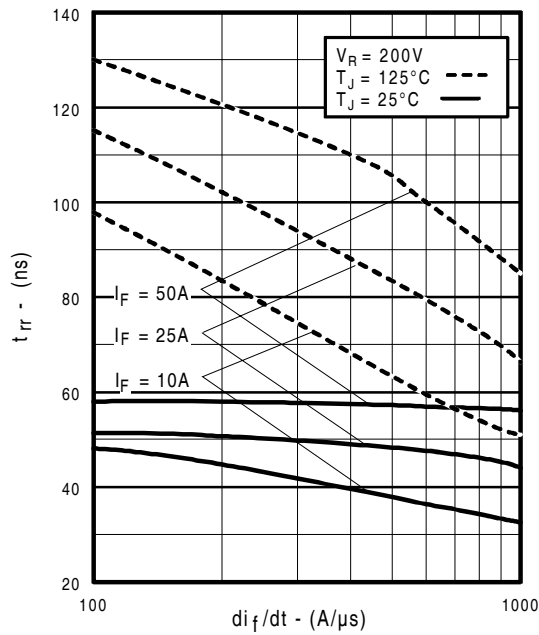


Fig. 14 - Typical Reverse Recovery vs. di_f/dt

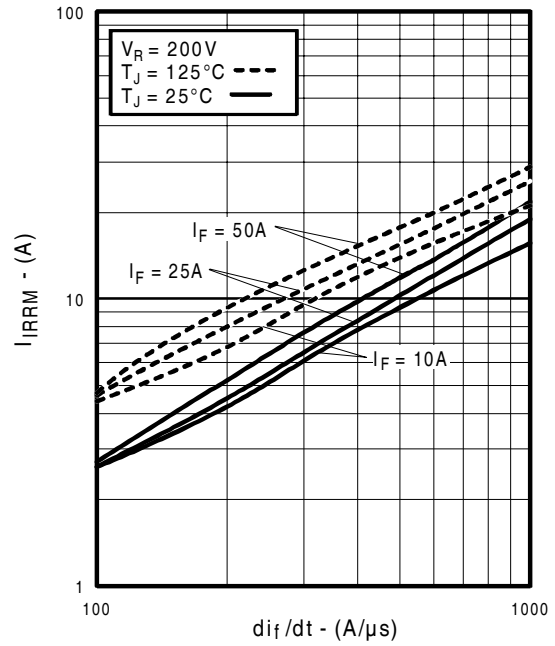


Fig. 15 - Typical Recovery Current vs. di_f/dt

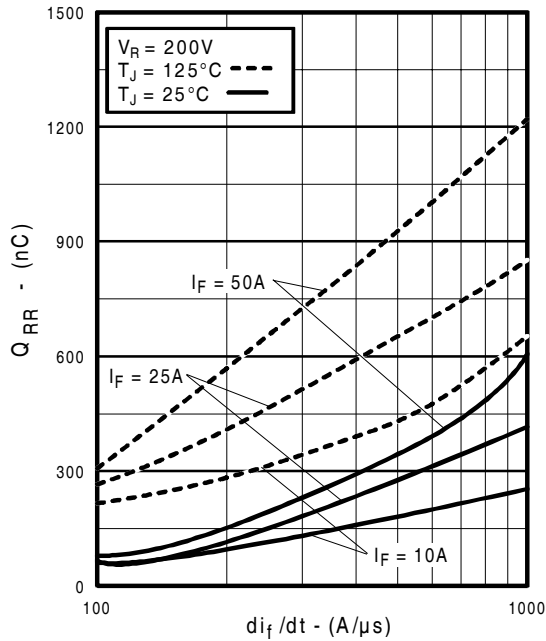


Fig. 16 - Typical Stored Charge vs. di_f/dt

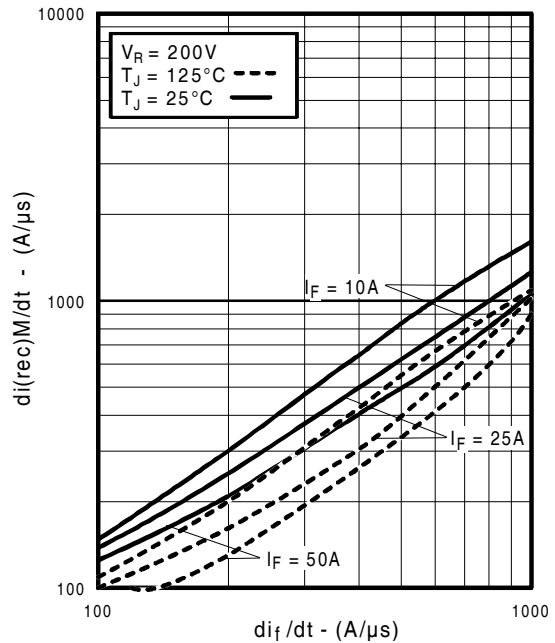


Fig. 17 - Typical $di_{(rec)M}/dt$ vs. di_f/dt

IRG4PC50UDPbF

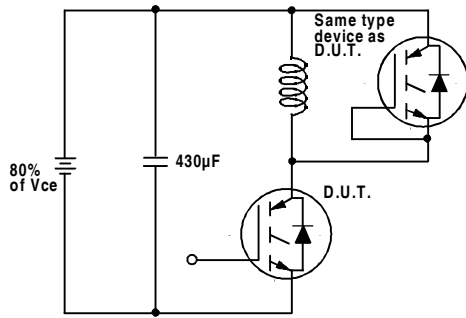


Fig. 18a - Test Circuit for Measurement of I_{LM} , E_{on} , $E_{off}(\text{diode})$, t_{rr} , Q_{rr} , I_{rr} , $t_{d(on)}$, t_r , $t_{d(off)}$, t_f

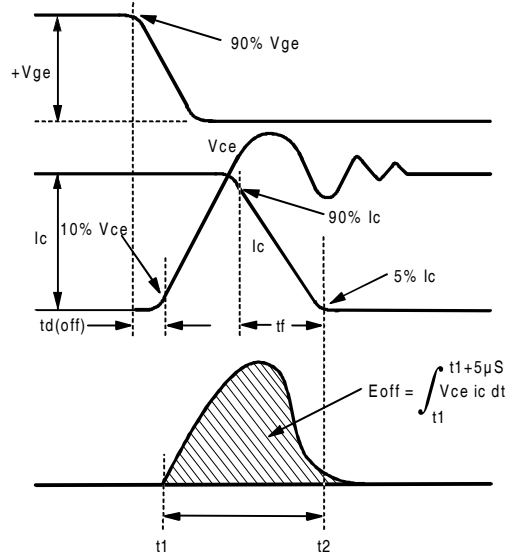


Fig. 18b - Test Waveforms for Circuit of Fig. 18a, Defining E_{off} , $t_{d(off)}$, t_f

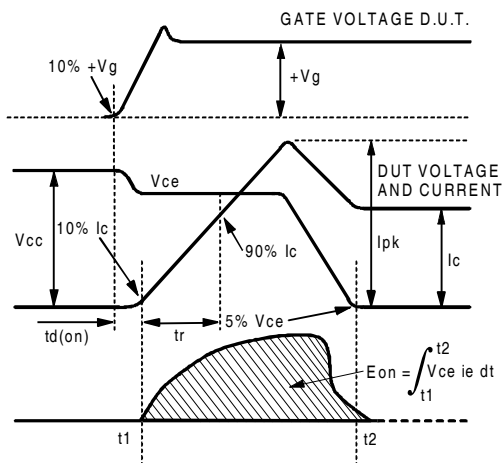


Fig. 18c - Test Waveforms for Circuit of Fig. 18a, Defining E_{on} , $t_{d(on)}$, t_r

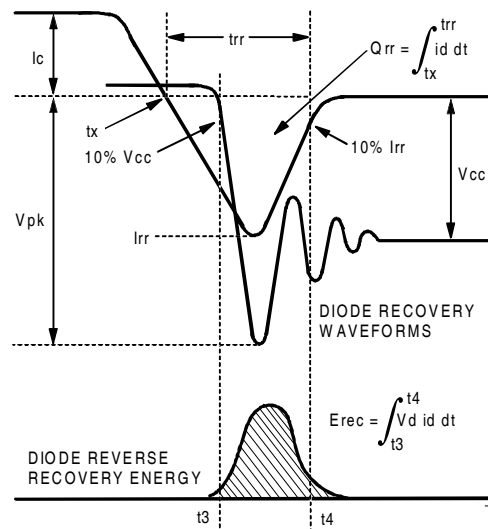


Fig. 18d - Test Waveforms for Circuit of Fig. 18a, Defining E_{rec} , t_{rr} , Q_{rr} , I_{rr}

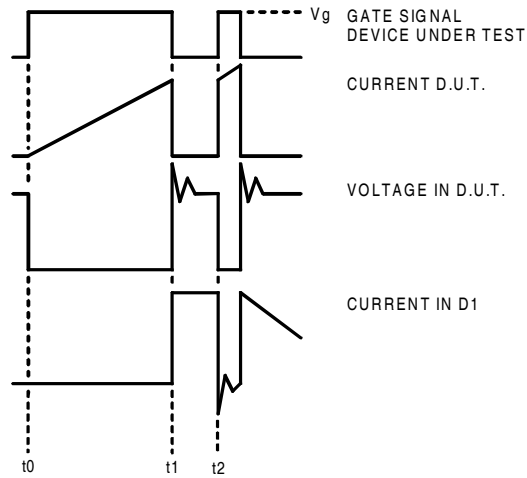


Figure 18e. Macro Waveforms for Figure 18a's Test Circuit

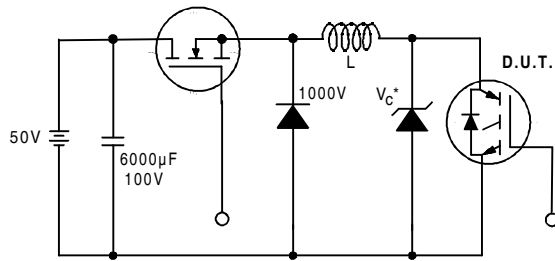


Figure 19. Clamped Inductive Load Test Circuit

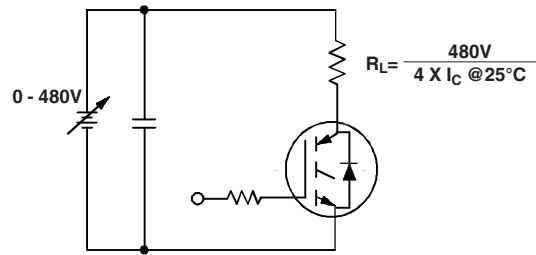


Figure 20. Pulsed Collector Current Test Circuit

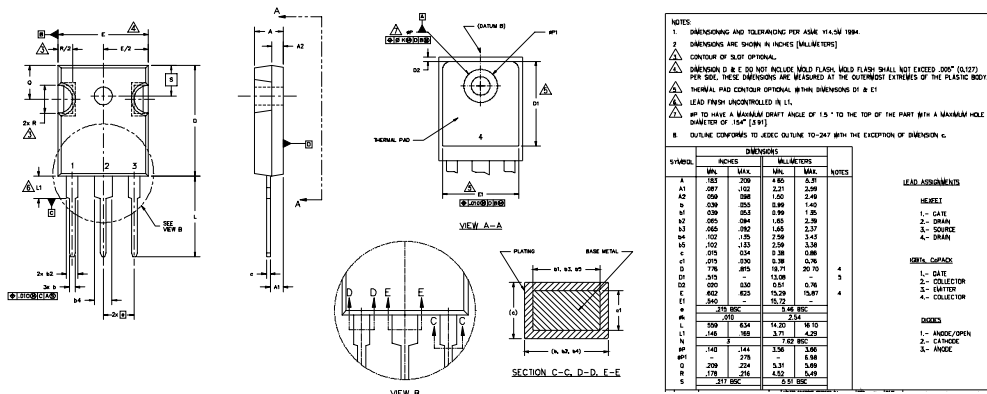
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Notes:

- ① Repetitive rating: $V_{GE} = 20V$; pulse width limited by maximum junction temperature (figure 20)
- ② $V_{CC} = 80\%(V_{CES})$, $V_{GE} = 20V$, $L = 10\mu H$, $R_G = 5.0\Omega$ (figure 19)
- ③ Pulse width $\leq 80\mu s$; duty factor $\leq 0.1\%$.
- ④ Pulse width $5.0\mu s$, single shot.

TO-247AC Package Outline

Dimensions are shown in millimeters (inches)



NOTES:

- DIMENSIONING AND TOLERANCING PER ASME Y14.5M 1994.
- DIMENSIONS ARE SHOWN IN INCHES (MILLIMETERS).
- CONTOUR OF SLOT OPTIONAL.
- DIMENSION D & E DO NOT INCLUDE MOLD FLASH. MOLD FLASH SHALL NOT EXCEED .007" (0.177) PER SIDE. THESE DIMENSIONS ARE MEASURED AT THE OUTERMOST EXTREMITY OF THE PLASTIC BODY.
- THERMAL PAD CENTER OPTIONAL. OTHER DIMENSIONS OF B & F.
- LEAD FINISH UNCONTROLLED IN LT.
- MP TO HAVE A MAXIMUM DRAFT ANGLE OF 1.5° TO THE TOP OF THE PART WITH A MAXIMUM HOLE DIAMETER OF .104" (2.64).
- OUTLINE CONFORMS TO JEDEC OUTLINE 10-247 WITH THE EXCEPTION OF DIMENSION G.

SYMBOL	INCHES		MILLIMETERS		NOTES
	MIN.	MAX.	MIN.	MAX.	
A	.183	.209	4.65	5.31	
A1	.287	.102	7.31	2.59	
A2	.059	.058	1.50	1.49	
B	.039	.051	0.99	1.30	
B1	.050	.064	1.27	1.63	
B2	.065	.082	1.65	2.07	
B3	.102	.135	2.59	3.43	
B4	.102	.133	2.59	3.38	
B5	.075	.074	1.91	1.88	
C	.010	.030	0.25	0.76	
D	.776	.875	19.71	22.23	4
E	.050	.050	1.27	1.27	7
F	.602	.825	15.29	20.97	4
G	.342		8.74		
H	.215 BSC		5.46 BSC		
I	.500 BSC		12.70 BSC		
J	.140	.160	3.55	4.06	
K	.140	.144	3.56	3.66	
M	.275		7.00		
N	.209	.226	5.31	5.79	
O	.178	.216	4.52	5.49	
S	.117 BSC		2.97 BSC		

LEAD ASSIGNMENTS

HEXLET

1- GATE
2- DRAIN
3- SOURCE
4- DRAIN

DRIFT CAPACITANCE

1- GATE
2- COLLECTOR
3- EMITTER
4- COLLECTOR

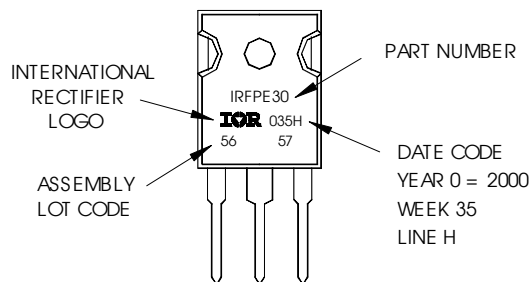
MARKING

1- ANODE OPEN
2- CATHODE
3- ANODE

TO-247AC Part Marking Information

EXAMPLE: THIS IS AN IRFPE30
WITH ASSEMBLY
LOT CODE 5657
ASSEMBLED ON WW 35, 2000
IN THE ASSEMBLY LINE "H"

Note: "P" in assembly line
position indicates "Lead-Free"



Data and specifications subject to change without notice.

Note: For the most current drawings please refer to the IR website at:
<http://www.irf.com/package/>